PCI-EXPRESSx16 DL-DVI VGA HDMI 05/12 Page 1: P681-A01 OVERVIEW Page 01 1.Remove C690,C70 47uF Page 17 1.Remove 4-PIN FAN Circuit Page 2: PCI-EXPRESS INTERFACE Page 10 1.Remove J1 D-Sub Page 12 1.Change Q509 to Q513,Q514 SOT23 footprint Page 11 1.Remove R16,Q2 Page 16 1.Change FAN Screw hole Page 3: PARTITION A FRAME BUFFER INTERFACE Page 12 1.Remove R1,Q1 Page 20 1.Add C102 820uF Page 4: PARTITION A MEMORIES Page 16 1.Change Crystal Footprint to 2-PIN SMD 2.Remove C71 47uF Page 5: FBA DECOUPLING CAPS & NVVDD DECOUPLING CAPS Page 6: PARTITION C FRAME BUFFER INTERFACE Page 21 1.Remove D94 scottky diode Page 7: PARTITION C MEMORIES Page 17 1.Remove Thermal Sensor Circuit 05/19 Page 18 1.Remove U2,C54,R31,R30,D16 INFOROM circuit Page 11 1.Add EMI bridge Page 8: FBC DECOUPLING CAPS Page 19 1.Remove 3V3 to 1.8V circuit Page 12 2.Add EMI bridge Page 9: DACA (SOUTH DVI-I) 2.Change 5V REGULATOR Circuit Page 20 1.Change L8 Footprint to 1.6uH 05/21 Page 10: DACB (MID VGA) 2.Change Footprint to multi cap for EL 1500uF Page 03 1.Add RP24 termination risister Page 21 1.Change NVVDD to UP6161 Page 11: IFP AB (SOUTH DVI-I) Page 06 2.Add RP23 termination risister 2.Change L12 footprint to 1.2uH Page 12: IFP C (NORTH HDMI) 05/26 Page 13: IFP D (UNUSED) SWAP CMD Page 05 1. Remove Decoupling for EMI cap Page 03/06 RP5.1 , RP5.2 FBC_CMD10 , RP5.3 , RP5.4 FBC_CMD22 Page 14: IFP EF (UNUSED) Page 20 1. C84 change Footprint to multi cap RP4.1, RP4.2 FBC CMD18, RP4.3, RP4.4 FBC CMD7 Page 15: MIOA & MIOB RP24.1, RP24.2 FBA CMD30, RP24.3, RP24.4 FBA CMD7 RP20.1, RP20.2 FBA_CMD14, RP20.3, RP20.4 FBA CMD18 Page 16: XTAL, MECHANICALS, THERMALS Page 21 1.Add C39 270uF RP14.1, RP14.2 FBA_CMD1, RP14.3, RP14.4 FBA_CMD20 2.Add R922.R924 for APW7068 OCSET Page 17: EXTERNAL THERMAL SENSOR, FAN CONTROL, GPIO, JTAG RP12.3, RP12.4 FBA CMD29 Page 16 1.Add XTALIN R566 Risister Page 18: BIOS ROM, HDCP ROM, STRAPPING OPTIONS Add XTALOUT R573 Risister 05/27 Page 02 1.Change C51 to 0805 1UF and ADD C54 0805 1UF Page 19: LINEAR POWER SUPPLIES Page 05 1. Add Decoupling for EMI cap C80,C524,C517,C102 Page 03 1.C642,C666,C633 change to .01UF Page 20: FBVDDQ/PEXVDD POWER SUPPLY Page 05 1.Remove C516,C525,C549,C556,C541,C512 Remove C513,C546,C540,C528,C547,C507 Page 21: NVVDD POWER SUPPLY Remove C544, C545, C520, C523, C532, C508 Remove C535, C526, C543, C553, C537, C88 07/30 01. Create V805-0A base on MS-V804-0A change to DDR2 Memory Page 08 1.Remove C566,C567,C576,C578,C82,C564 02. DDR2 Memory schematic copy from MS-V202-0A Remove C619, C592, C586, C585, C622, C574 03. Reserve GPIO[5:6] NVVDD switch , NVVDD state = 0.9V(00) , 1V(10) , 1.0625V(11) Remove C705,C706,C680,C729,C691,C683 04. remove JTAG Remove C742, C738, C731, C725, C743, C728 05. remove HDCP ROM Page 20 1.Remove C86,C562,C563,C87 06. remove FAN control , for 12V full speed 07. remove DAC EMI filter & ESD Diode & remove pi type left side cap 08, modify 5V circuit to TO-252 package 09. remove PWM NVVDD OCSET , Chage 10Kohm parallel low-side MOSFET VGS 10. remove R576 net IFP_PLLVDD change to 3V3 11. decrease caps 12. modify NVVDD & FBVDD PWM compensation value
13. MIOA_VDDQ net to GND > MIOA_CLKIN net to NC ASE LEVEL GENERIC SCHEMATIC ONLY, COMMON & NO. STUFF ASSEMBLY NOTES AND BOM NOT FIN 14. del PEX_PLLVDD SUPPLY circuit TOTAL SOURCE TOWNS TO ANY CONTROL TOWNS CONTROL TOWN CONTROL TOWNS CONTROL TOWNS CONTROL TOWN CONTROL T SKU0001 SKU0002 SKU0011 <UNDEFINED> <UNDEFINED> <UNDEFINED> 15. add NVVDD & FBVDD 12V input SMD choke overlap 0805 / 0 ohm 16. NVVDD & FBVDD 12V input DIP cap change to 3 pin 17. overlap NVVDD & FBVDD output choke UNDEFINED UNDEFINED NVIDIA CORPORATION

600-10681-base-100 A

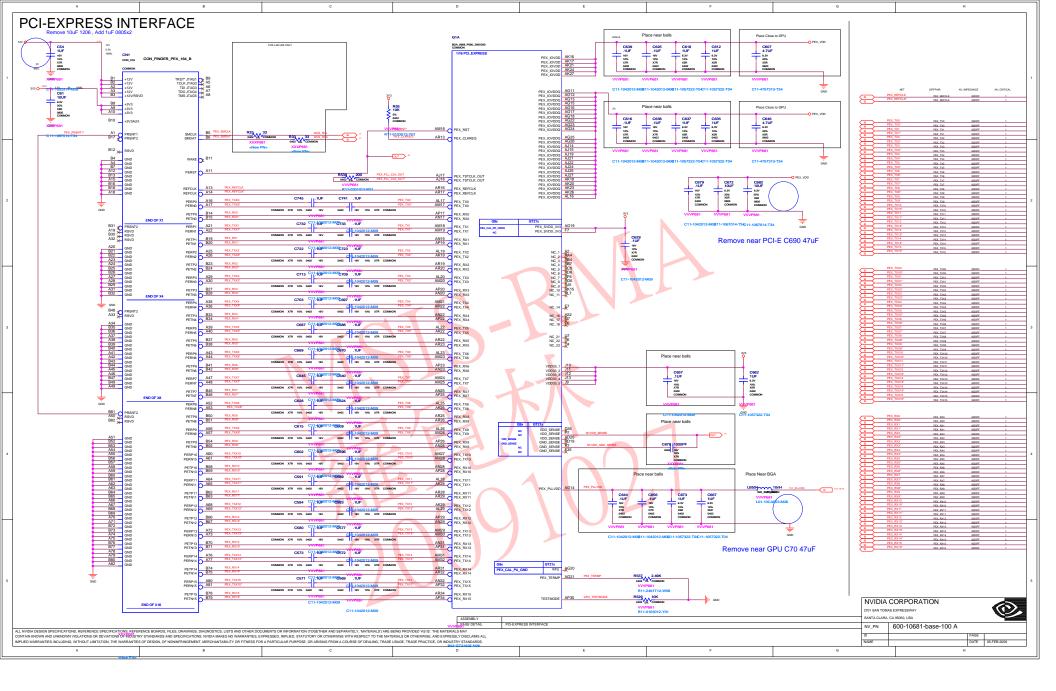
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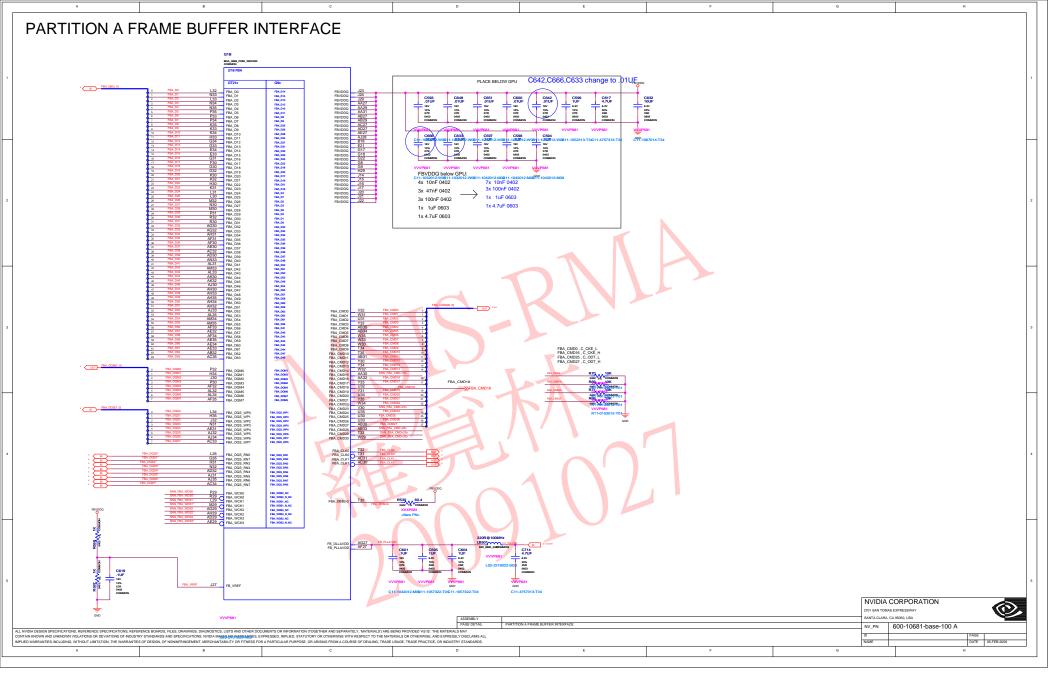
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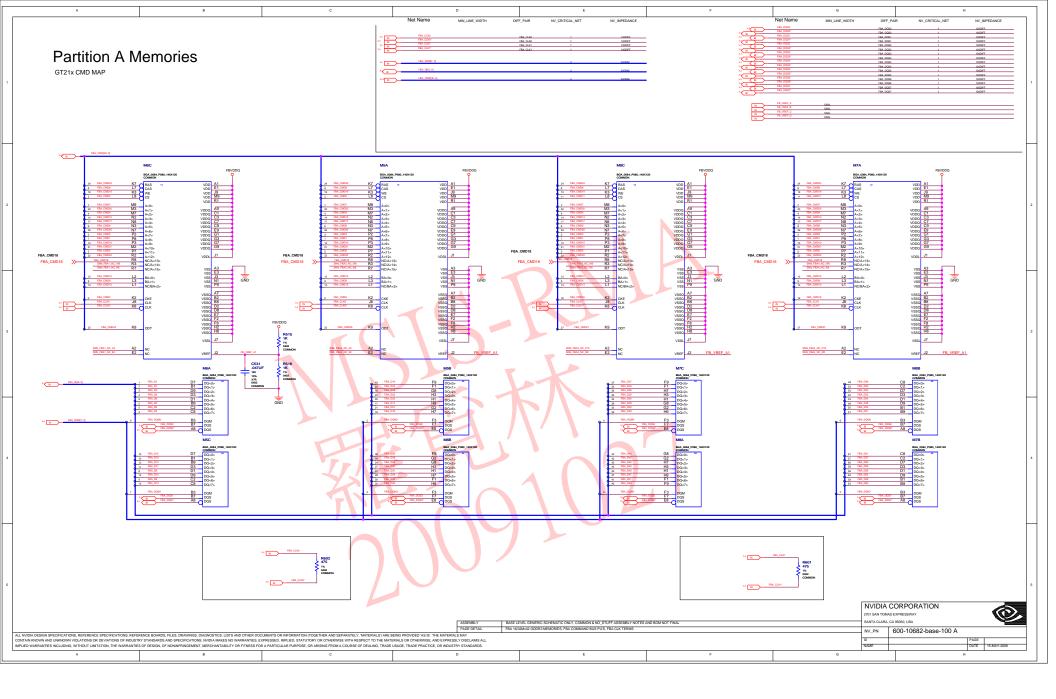
V805-10

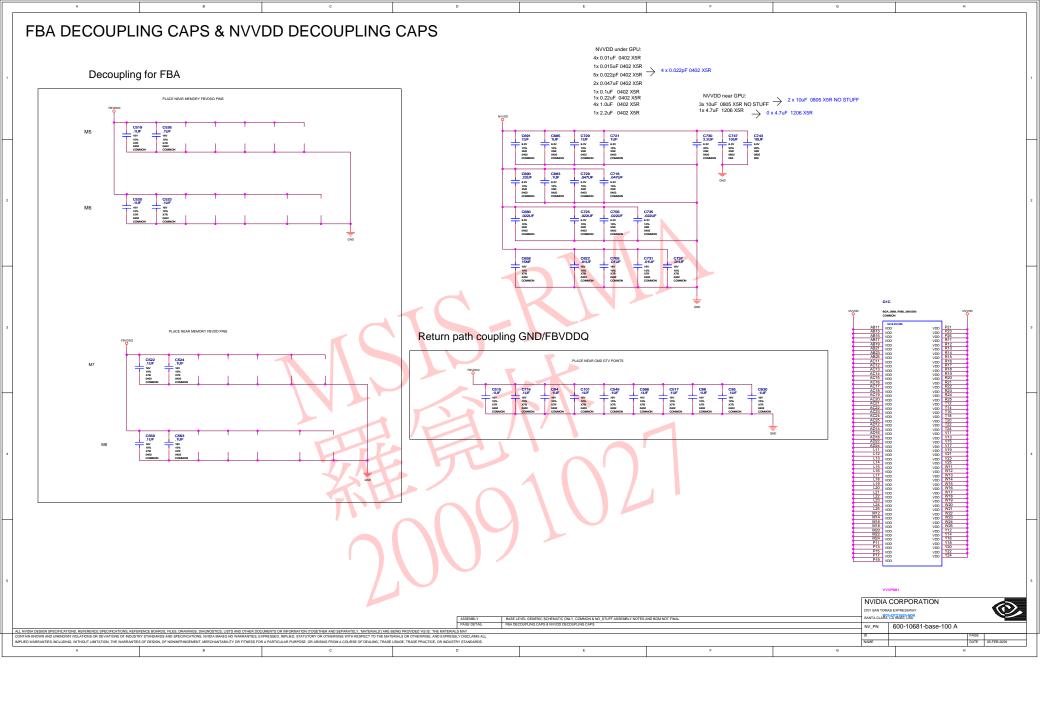
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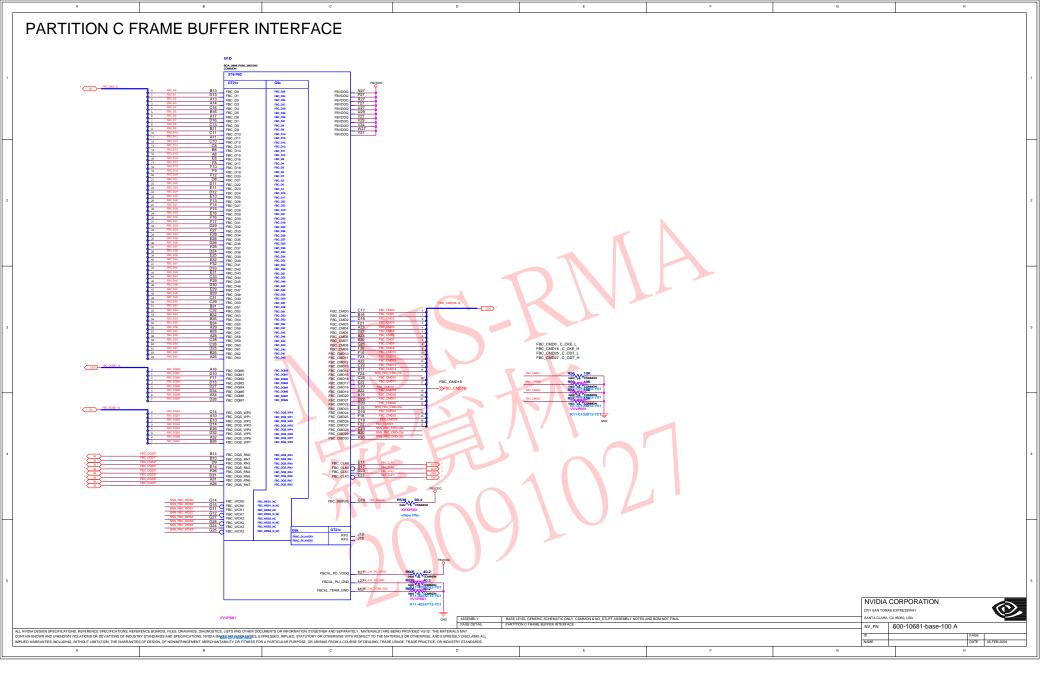
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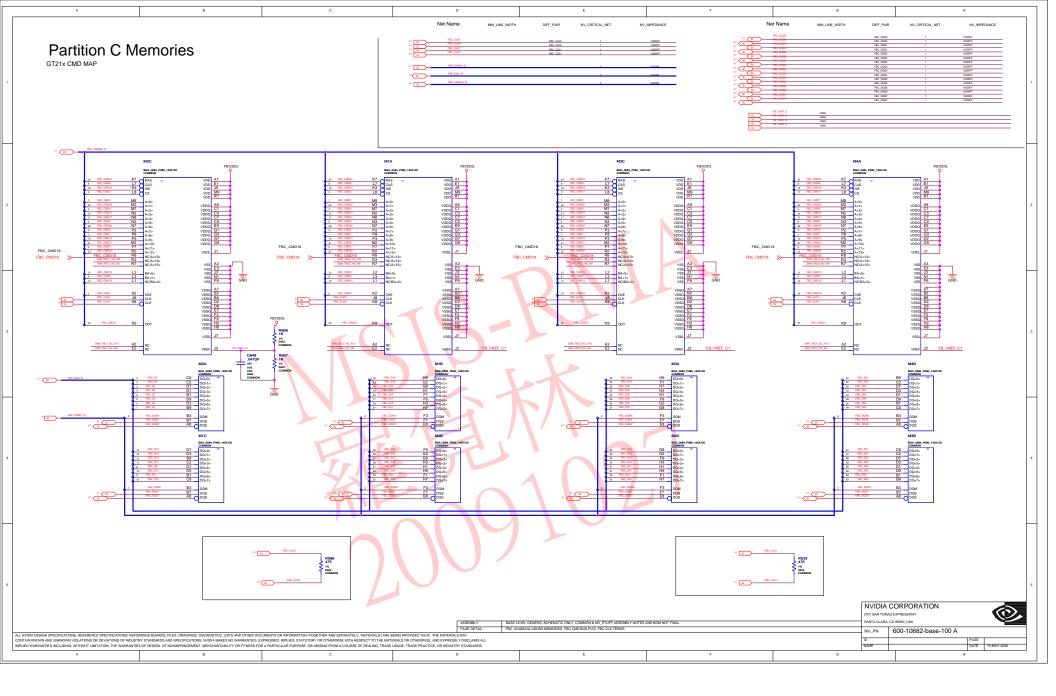


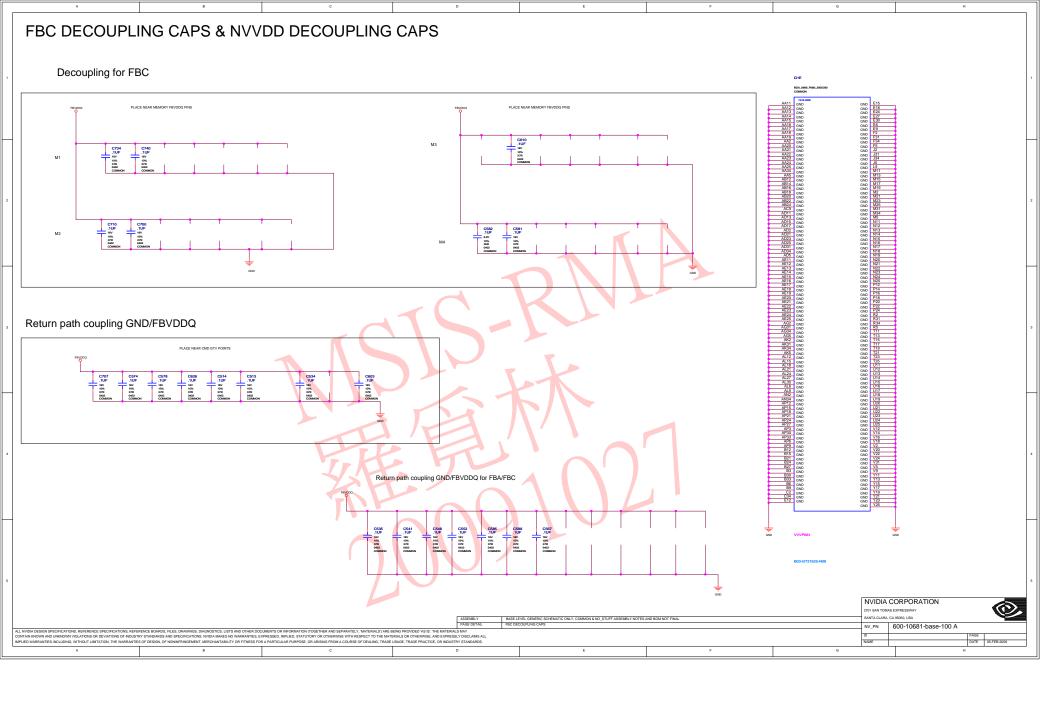


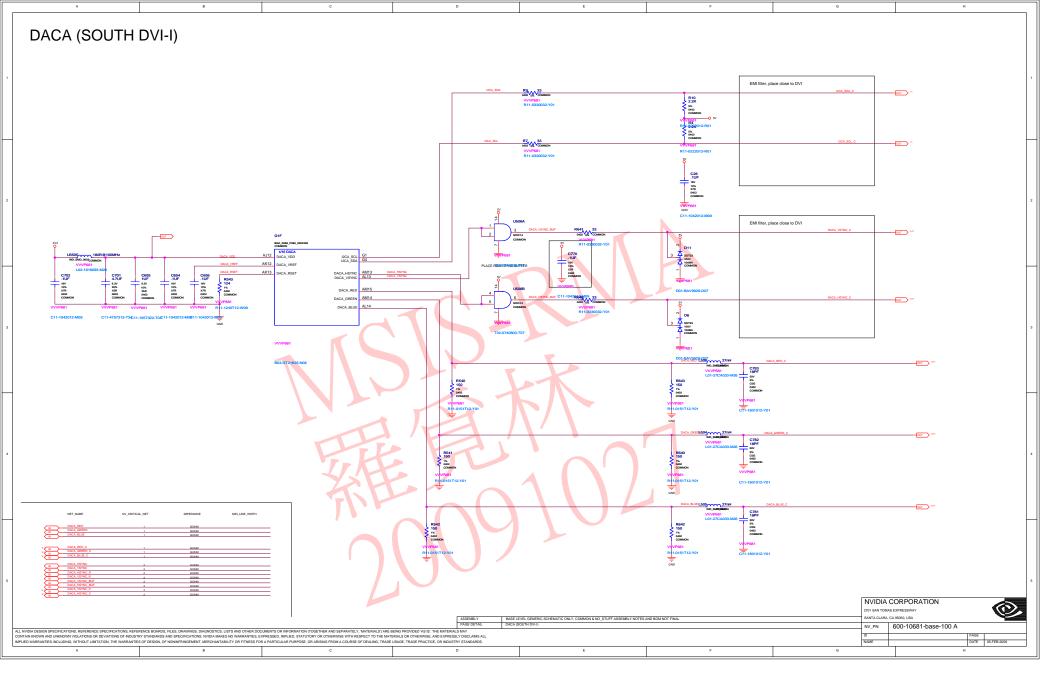


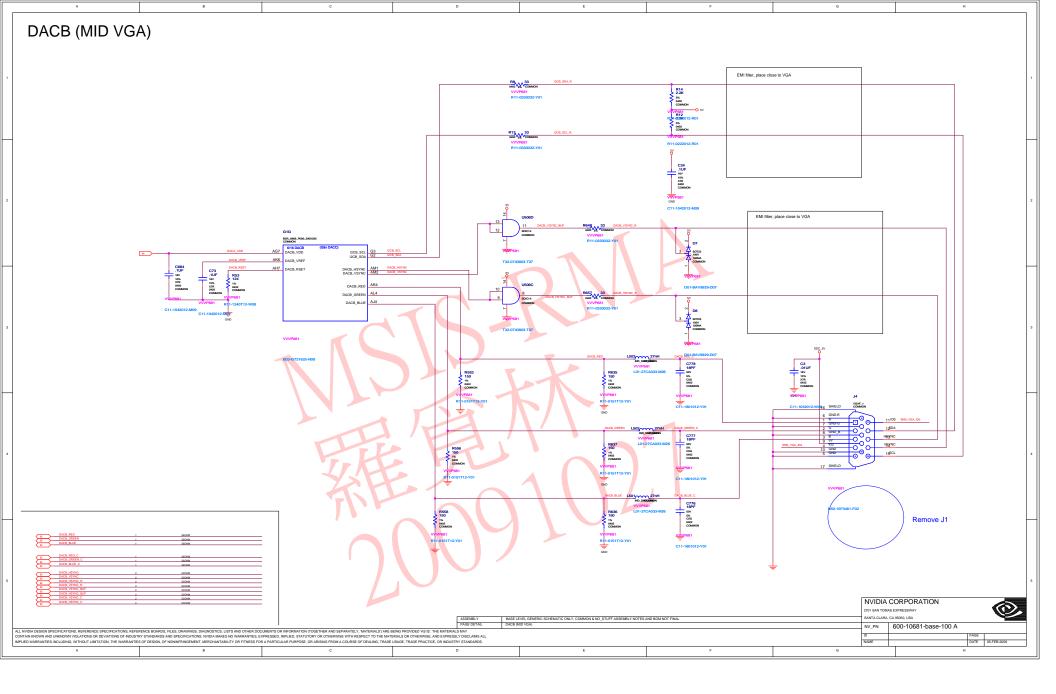


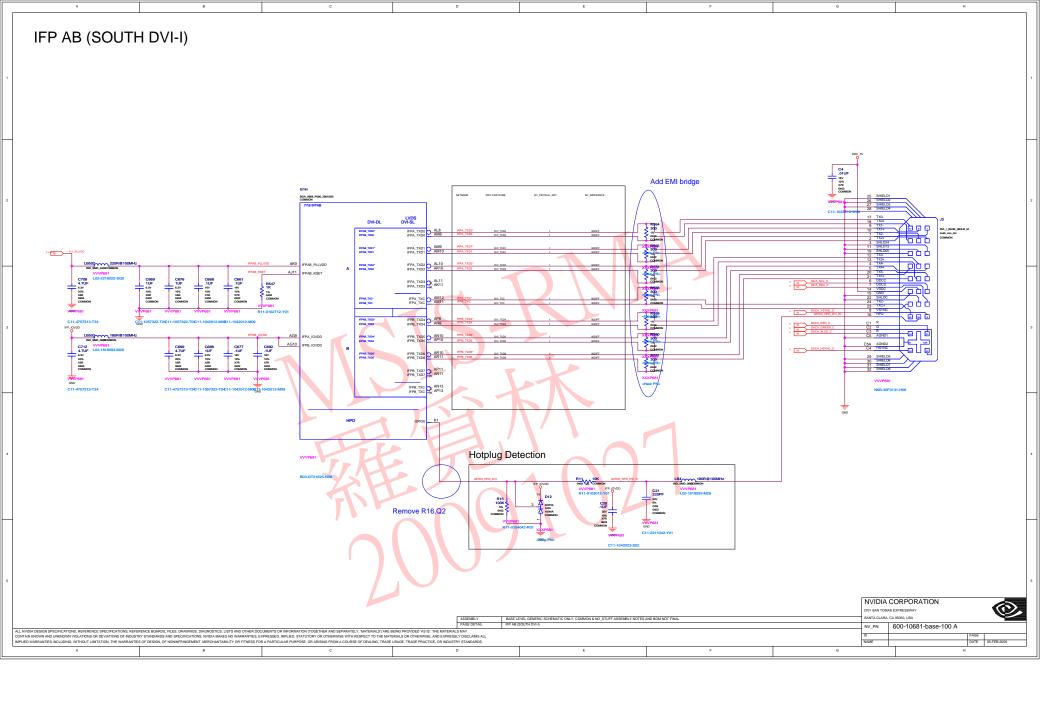


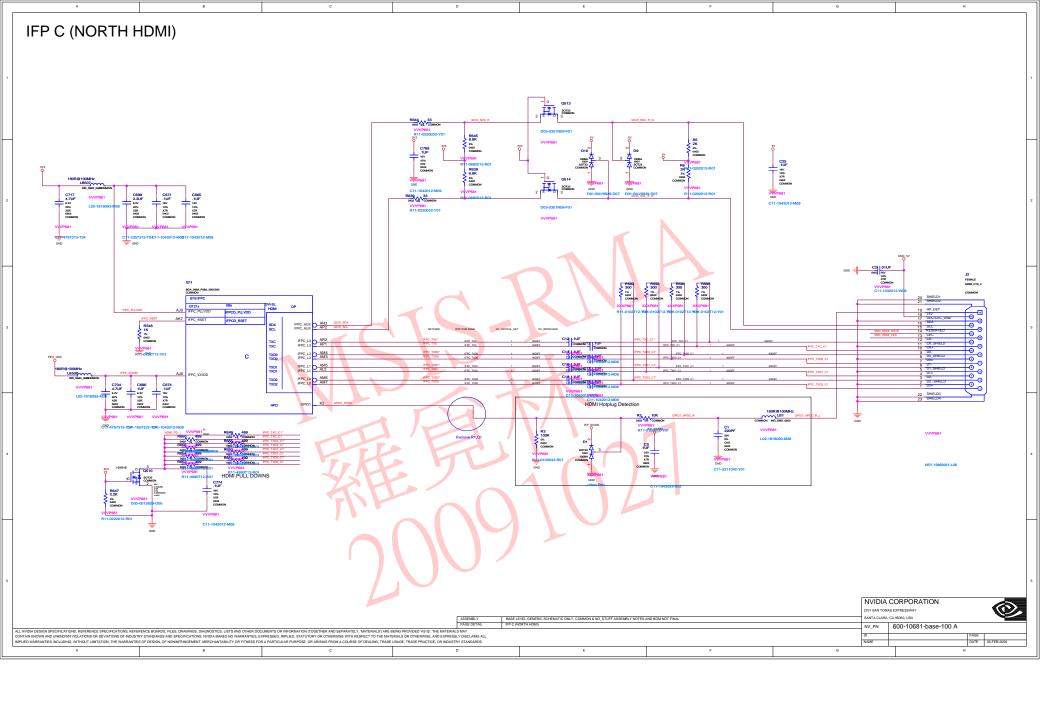


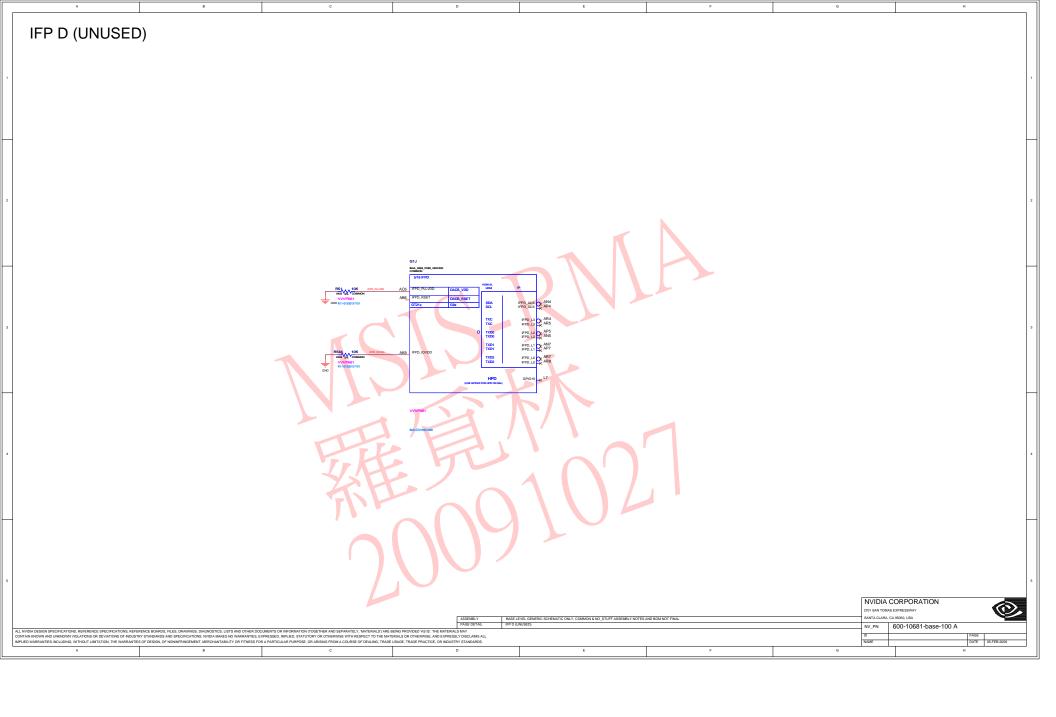


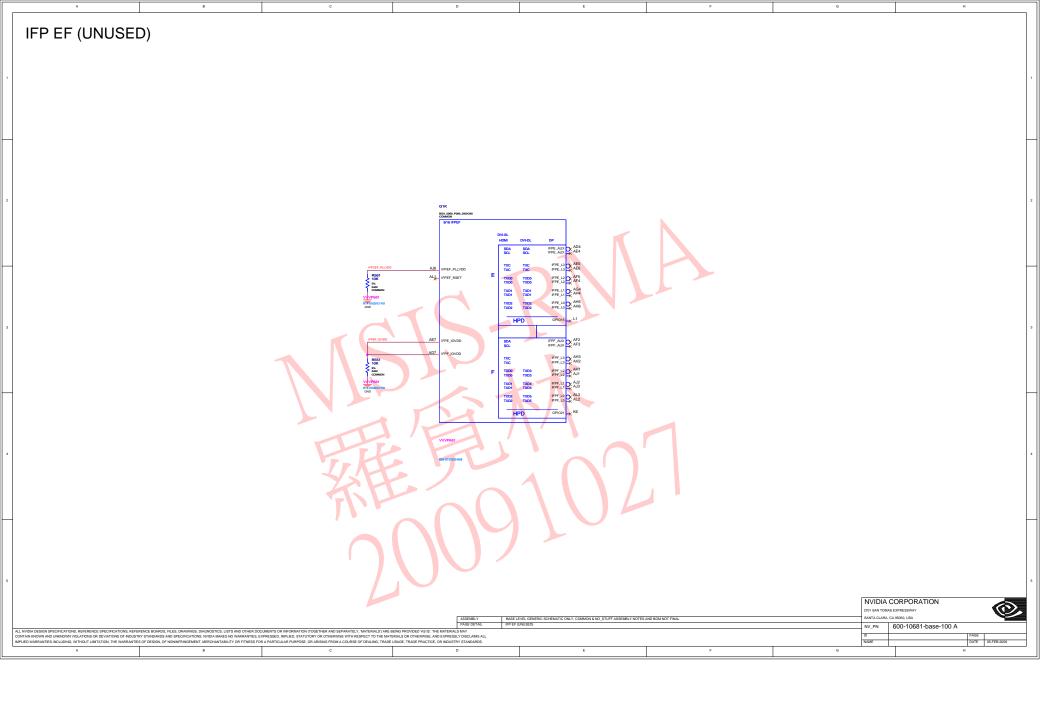


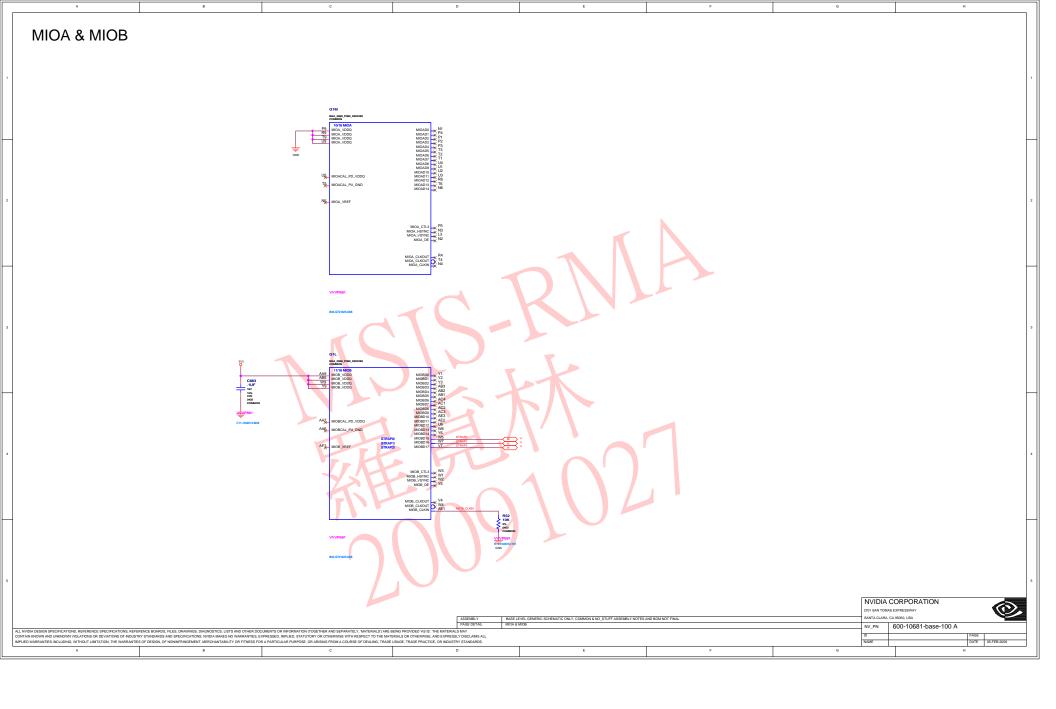


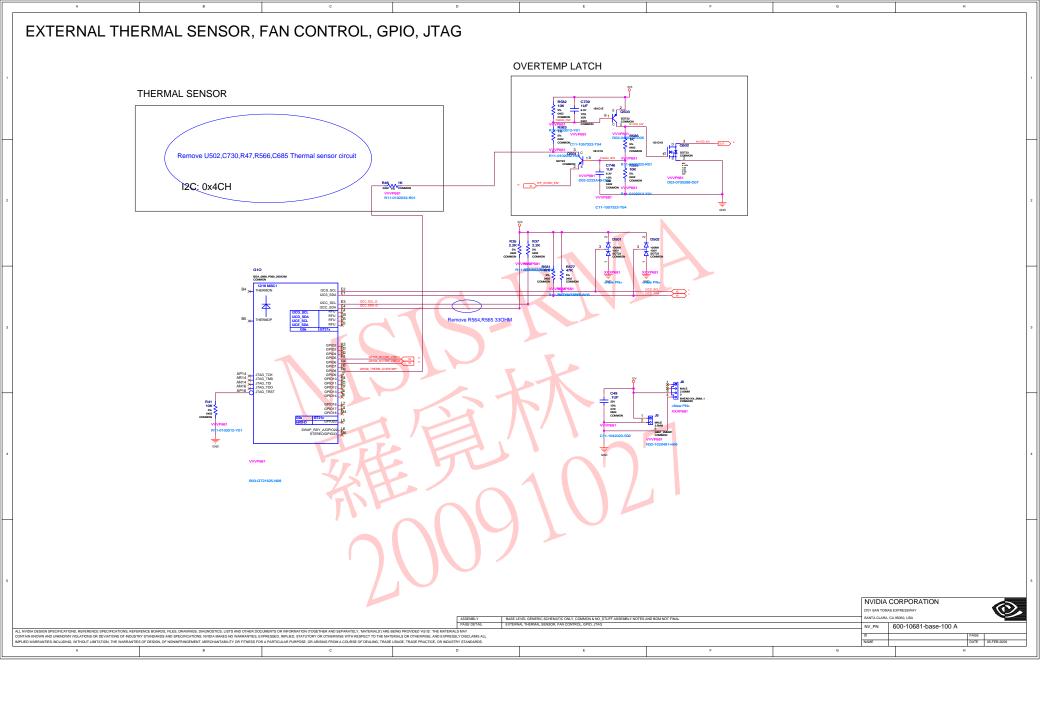


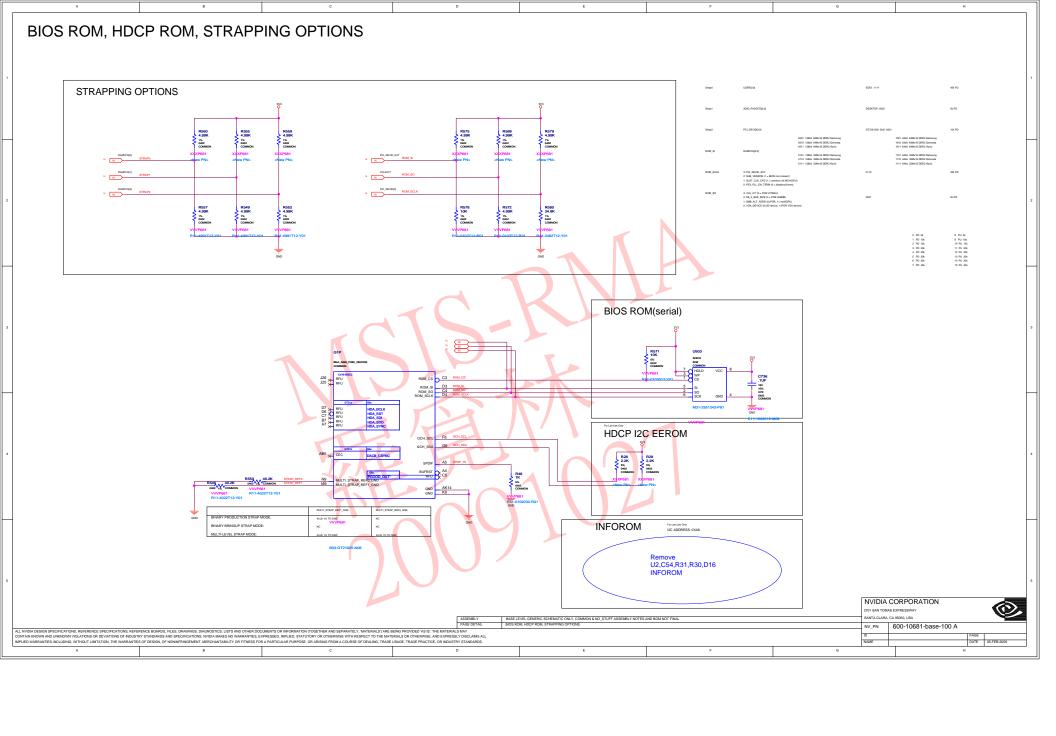


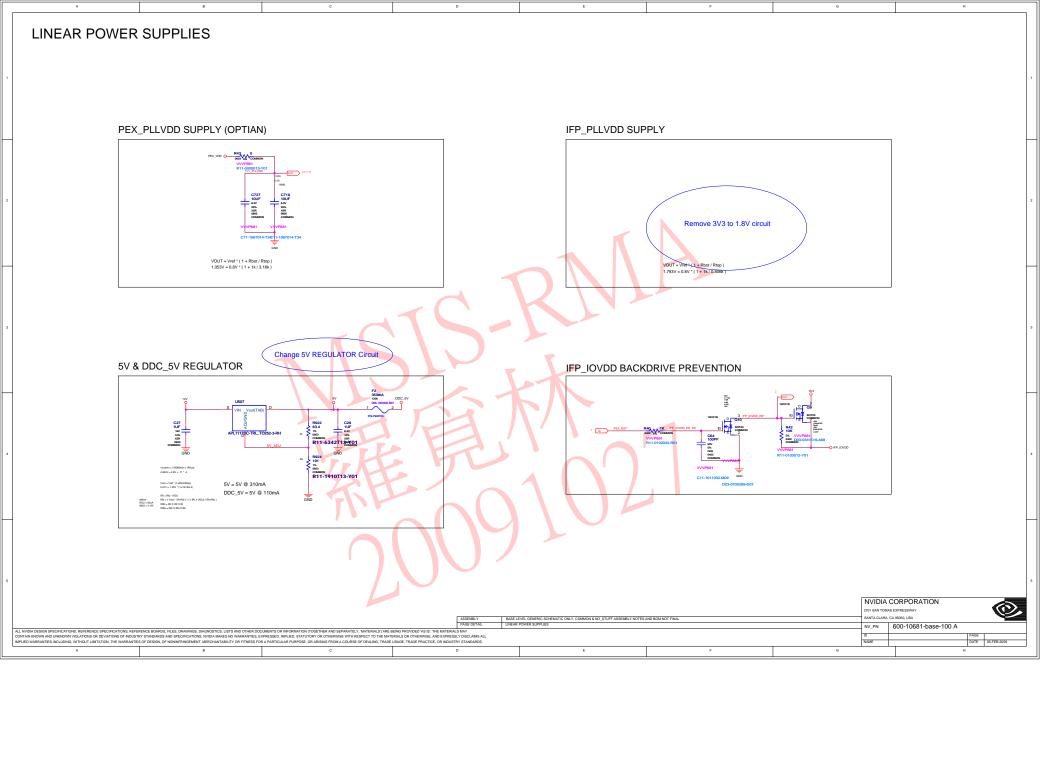


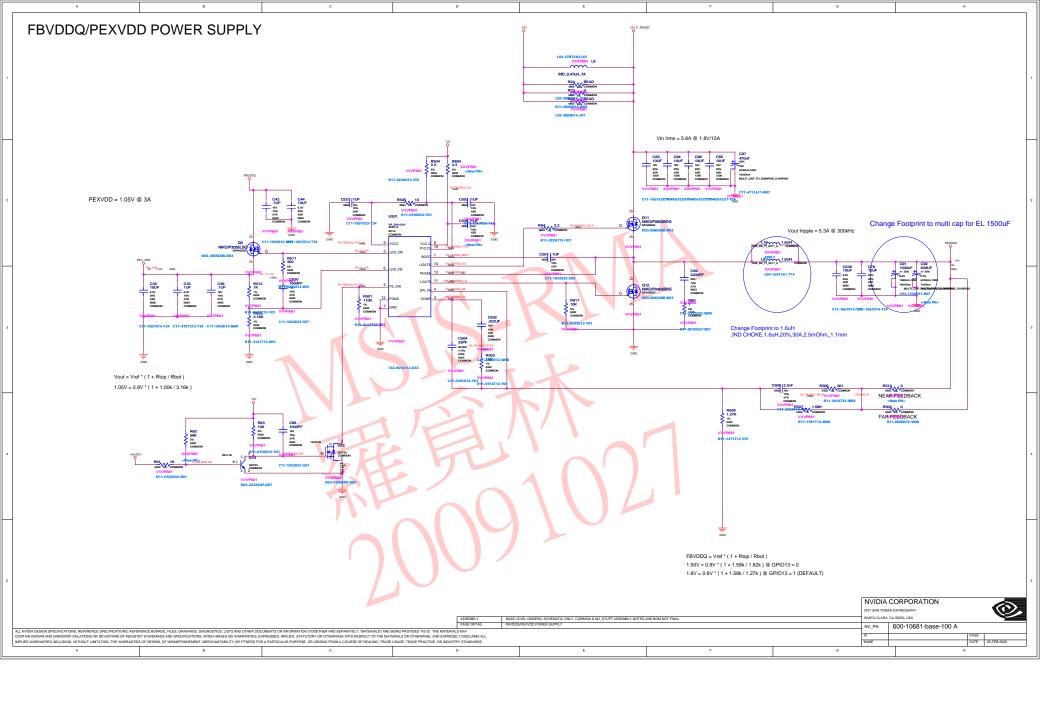


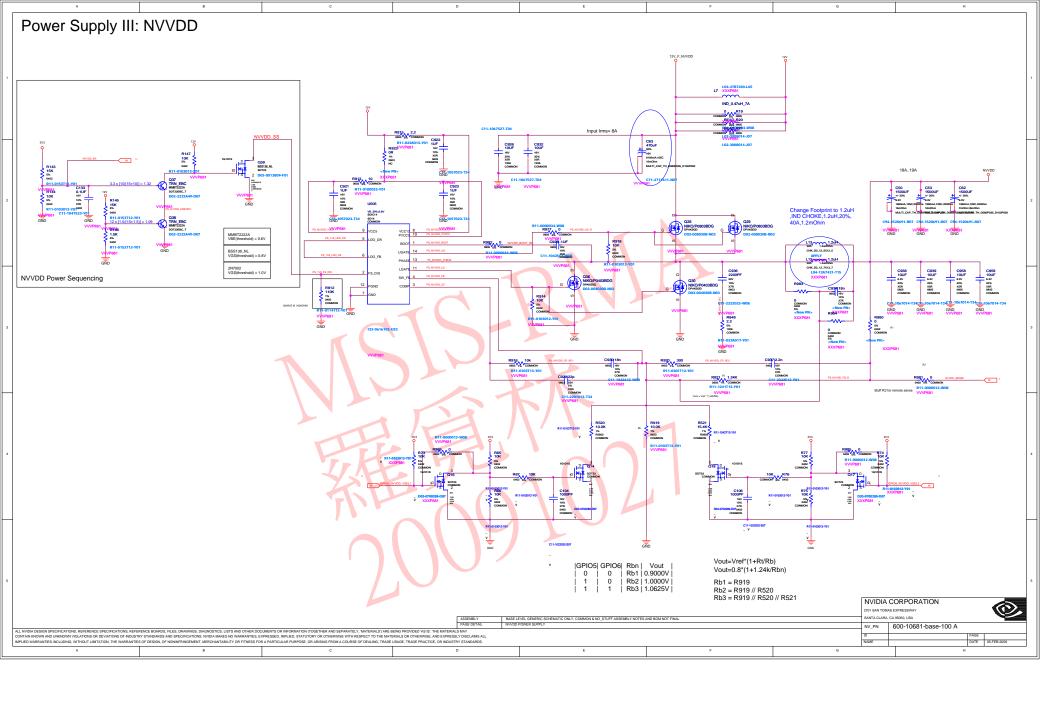












XTAL, MECHANICALS, THERMALS

